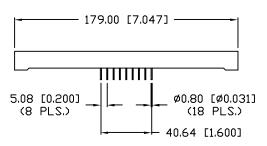
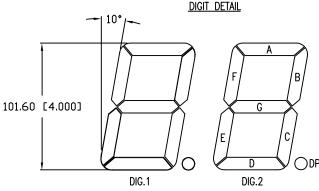
UNCONTROLLED DOCUMENT

PIN 18 ¬

PIN 1

PIN 10 PIN 9





15.00 [0.591] -- 7.70 [0.303] 122.00 [4.803] 107.00 [4.213]

CAUTION: STATIC SENSITIVE DEVICE FOLLOW PROPER E.S.D. HANDLING PROCEDURES WHEN WORKING WITH THIS PART.

PART NUMBER LDD-CA402RI-UPG

REV.

ELECTRO-OPTICAL CHARACTERISTICS TA=25°C If=10mA

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND	
PEAK WAVELENGTH		525		nm		
FORWARD VOLTAGE *		17.5/3.5	20.0/4.0	V_f		
REVERSE VOLTAGE	5.0			V_r	I _r =100μA	
AXIAL INTENSITY		7000		μcd	$I_f = 10mA$	
EMITTED COLOR:	GREEN					
FACE COLOR:	GRAY					
SEGMENT COLOR:	MILKY WHITE DIFFUSED					
·						

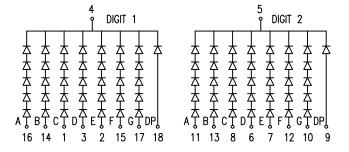
^{*} SECOND VALUE IS FOR DECIMAL POINT.

LIMITS OF SAFE OPERATION AT 25°C PER DIE

PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT*	150	mA
STEADY CURRENT	25	mA
POWER DISSIPATION	120	mW
DERATE FROM 25°C	- 1.2	mW/°C
OPERATING, STORAGE TEMP.	- 40 TO +85	° C
SOLDERING TEMP.	+ 260	. C
2.0mm FROM BODY		3 SEC. MAX
* 1 440 C		

^{*} t<10µS

COMMON CATHODE



UNCONTROLLED

*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), X.X=±0.5 (±0.020), X.XX=±0.25 (±0.010), X.XXX=±0.127 (±0.005). LEAD SIZE=±0.05 (±0.002), LEAD LENGTH=±0.75 (±0.030), MIN= +DECIMAL PRECISION MAX.= +0.00 (±0.005). LEAD SIZE=±0.05 (±0.002), LEAD SIZE=±0.05 (±0.000), LEAD SIZ

290 E. HELEN ROAD PALATINE, IL 60067-6976 PHONE: +1.847.359.2790 US WEB: www.lumex.com TW WEB: www.lumex.com.tw

DRAWN BY:

CHECKED BY: APPROVED BY: DATE:

7.31.03 PAGE: 1 OF 1 SCALE: N/A

REV. PART NUMBER LDD-CA402RI-UPG

4.00" SEVEN SEGMENT, DUAL DIGIT, LED DISPLAY, 525nm GREEN CHIPS, GRAY FACE WITH WHITE SEGMENTS, COMMON CATHODE, 18 PINS, MULTIPLEXED.

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OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.